Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**Top Material: Aluminum**

**Backside Material: Silicon**

**Bond Pad Size: .004” Square**

**Backside Potential:**

**Mask Ref: MG-157**

**APPROVED BY: DK DIE SIZE .045 x .064” DATE: 1/3/17**

**MFG: Motorola Semi THICKNESS .015” P/N: LM117L**

**DG 10.1.2**

#### Rev B, 7/1